

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (currently amended) An apparatus comprising:

a thermal conductor; and

a portion of solder material ~~coupled~~ primarily pressure-clad to a first side of the thermal conductor,

wherein a substantially voidless interface exists between the portion of solder material and the first side of the thermal conductor.

2. (currently amended) An apparatus according to Claim 1, further comprising:

a second portion of solder material primarily pressure-clad to a second side of the thermal conductor,

wherein a second substantially voidless interface exists between the second portion of solder material and the second side of the thermal conductor.

3. (original) An apparatus according to Claim 2, wherein a surface area of the second portion of solder material is greater than a surface area of the first portion of solder material.

4. (currently amended) An apparatus comprising:

an integrated heat spreader comprising a portion of solder material primarily pressure-clad to and a first side of a thermal conductor,

wherein a substantially voidless interface exists between the solder material and ~~a~~the first side of the thermal conductor.

5. (original) An apparatus according to Claim 4, further comprising:

an integrated circuit die coupled to a first side of the integrated heat spreader,

wherein the portion of solder material is disposed on the first side of the integrated heat spreader.

6. (original) An apparatus according to Claim 5, further comprising:

an integrated circuit package coupled to the integrated circuit die.

7. (original) An apparatus according to Claim 5, further comprising:

a heat sink coupled to a first side of the integrated heat spreader.

8. (original) An apparatus according to Claim 7, wherein the portion of solder material is disposed on a second side of the integrated heat spreader.

9. (currently amended) An apparatus according to Claim 8, wherein the integrated heat spreader comprises a second portion of solder material primarily pressure-clad to~~disposed on~~ the first side of the integrated heat spreader.

10. (original) An apparatus according to Claim 9, wherein a surface area of the second portion of solder material is greater than a surface area of the first portion of solder material.

11.-19. (cancelled)

20. (currently amended) A system comprising:

a microprocessor comprising:

an integrated heat spreader comprising a portion of solder material primarily pressure-clad to~~and~~ a thermal conductor, wherein a substantially voidless interface exists between the solder material and a first side of the thermal conductor; and

an integrated circuit die coupled to the solder material; and

a double data rate memory electrically coupled to the integrated circuit die.

21. (original) A system according to Claim 20, further comprising:

a motherboard electrically coupled to the integrated circuit die and to the memory.

22. (currently amended) A system according to Claim 20, the integrated heat spreader further comprising:

a second portion of solder material primarily pressure-clad to a second side of the thermal conductor,

wherein a second substantially voidless interface exists between the second portion of solder material and ~~a~~ the second side of the thermal conductor.

23. (original) A system according to Claim 22, the microprocessor further comprising:
a heat sink coupled to the second solder material.